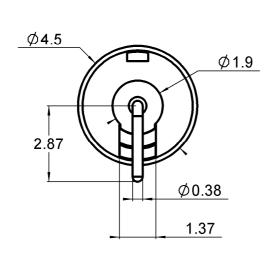
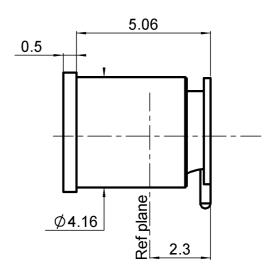
SMT TYPE - LIMITED DETENT - REEL 500

R222.508.310

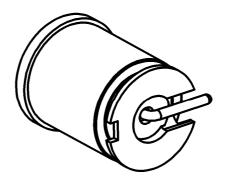
Series: SMP







All dimensions are in mm.





		<u></u>
COMPONENTS	MATERIALS	PLATING (μm)
BODY OUTER CONTACT INSULATOR GASKET OTHERS PARTS CENTER CONTACT	BRASS STAINLESS STEEL PTFE BERYLLIUM COPPER	GOLD 0.1 TO 0.4 OVER NICKEL 2 GOLD 0.1 TO 0.4 OVER NICKEL 2 TIP: GOLD 1.3 OVER NICKEL2 REAR: GOLD FLASH OVER NICKEL2
		l

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In the effort to improve our products, we reserve the right to make changes judged to be



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Series: SMP

PACKAGING

Standard Unit Other 500 Contact us

SPECIFICATION

ENVIRONMENTAL

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-18} \;\; \text{GHz} \end{array}$

Operating temperature -65/+165 ° C Hermetic seal NA Atm.cm3/s

VSWR 1.15* + 0,0000 x F(GHz) Maxi

Panel leakage NA

Insertion loss RF leakage 0.12 $\sqrt{F(GHz)}$ dB Maxi RF leakage - (NA - F(GHz)) dB Maxi

NA - F(GHz)) dB **335** Veff Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage 500 Veff mini Insulation resistance 5000 M Ω mini

OTHER CHARACTERISTICS

Assembly instruction

Others:

C

Compliant with MIL-STD-348
*At 12.4GHz - Performance strongly depends on lay out and pcb material

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0,3200** g

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ges judged to be RADIALLS

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Series: SMP

SOLDER PROCEDURE

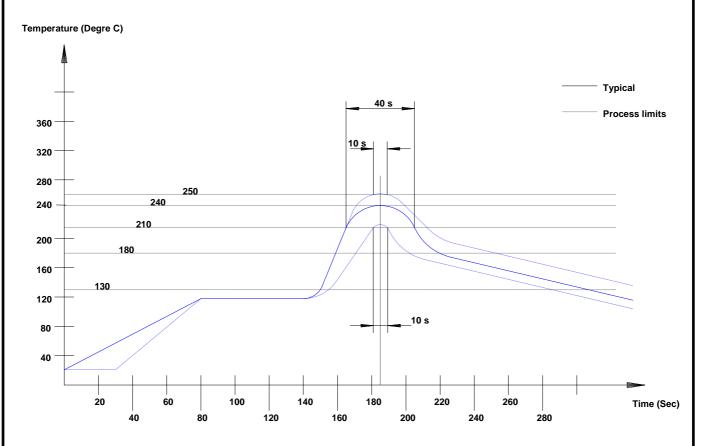
1. Deposit solder paste 'Sn Pb 60-40' on mounting zone by screen printing application. We recommend a low residue flux.

We advise a thickness of 150 μm .

Verify that the edges of the zone are clean.

- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is prefered to check the positioning of the component. Adhesive agents are forbidden on the receptacle.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFIL



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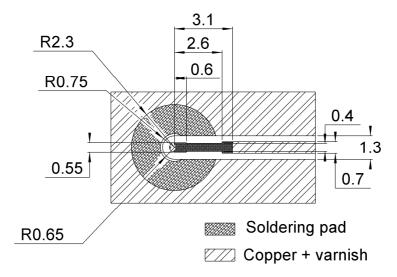
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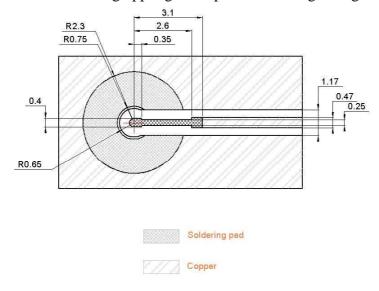
Series: SMP

RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



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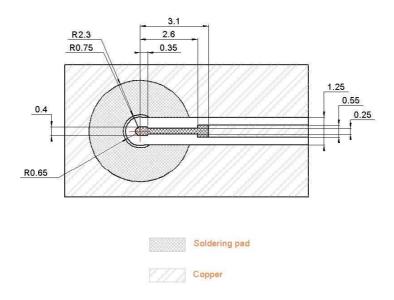


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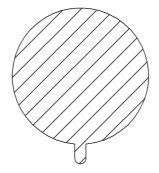
SMT TYPE - LIMITED DETENT - REEL 500

Series: SMP

Substrate: RO6002 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



SHADOW OF THE RECEPTACLE



FOR VIDEO CAMERA

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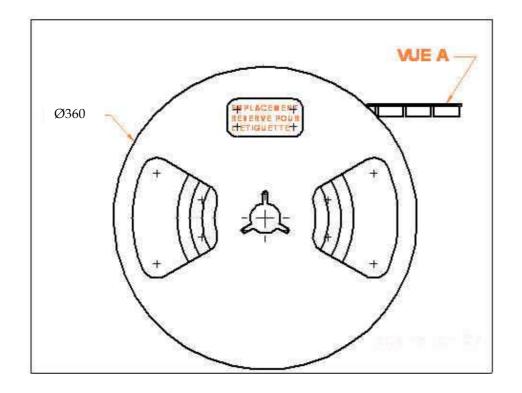
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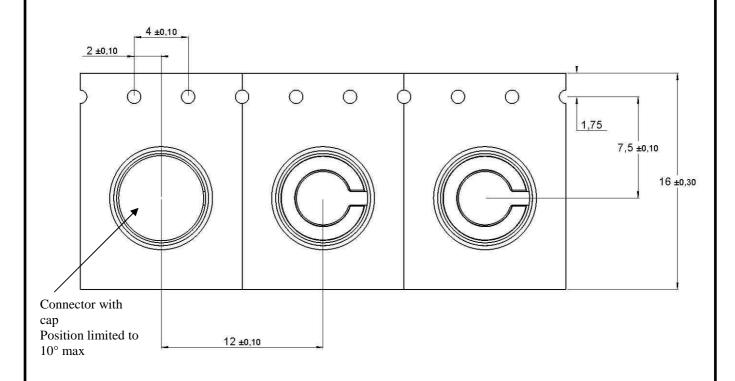


SMT TYPE - LIMITED DETENT - REEL 500

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Series: SMP





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